

具有 $\pm 12\text{kV}$ ESD 保护的 SN65C1168E-SEP 双路差动驱动器和接收器

1 特性

- VID V62/19606
- 耐辐射
 - 单粒子锁定 (SEL) 在 125°C 下的抗扰度可达 $43\text{MeV}\cdot\text{cm}^2/\text{mg}$
 - 在 $30\text{krad}(\text{Si})$ 的条件下无 ELDRS
 - 每个晶圆批次的 RLAT 总电离剂量 (TID) 高达 $20\text{krad}(\text{Si})$
- 增强型航天塑料
 - 受控基线
 - 金线
 - NiPdAu 铅涂层
 - 一个组装和测试基地
 - 一个制造基地
 - 支持军用 (-55°C 至 125°C) 温度范围
 - 延长了产品生命周期
 - 延长了产品变更通知
 - 产品可追溯性
 - 采用增强型模塑化合物实现低释气
- 达到或超出 TIA/EIA-422-B 和 ITU Recommendation V.11 标准的要求
- 由一个 5V 电源供电
- 为 RS-422 总线引脚提供 ESD 保护
 - $\pm 12\text{kV}$ 人体放电模型 (HBM)
 - $\pm 8\text{kV}$ IEC 61000-4-2, 接触放电
 - $\pm 8\text{kV}$ IEC 61000-4-2, 空气间隙放电
- 低脉冲偏斜

- 接收器输入阻抗 ... $17\text{k}\Omega$ (典型值)
- 接收器输入灵敏度 ... $\pm 200\text{mV}$
- -7V 至 7V 的接收器共模输入电压范围
- 无干扰上电/断电保护

2 应用

- 支持近地球轨道空间 应用
- 卫星通信
- 交流和伺服电机驱动器

3 说明

SN65C1168E-SEP 包含双驱动器和双接收器, 具有 $\pm 12\text{kV}$ ESD (HBM) 和 $\pm 8\text{kV}$ ESD (IEC61000-4-2 空气间隙放电和接触放电), 适用于 RS-422 总线引脚。此器件符合 TIA/EIA-422-B 和 ITU Recommendation V.11 标准的要求。经过 $20\text{krad}(\text{Si})$ TID 接触之后, 有些参数不符合所有的 TIA/EIA-422-B 和 ITU Recommendation V.11 要求。

SN65C1168E-SEP 驱动器具有单独的高电平有效使能端。

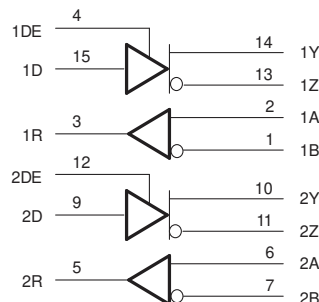
器件信息⁽¹⁾

器件型号	封装	封装尺寸 (标称值)
SN65C1168EMPWTSEP	TSSOP (16)	5.00mm $\times$ 4.40mm
SN65C1168EMPWSEP		

(1) 如需了解所有可用封装, 请参阅数据表末尾的可订购产品附录。

方框图

SN65C1168E-SEP



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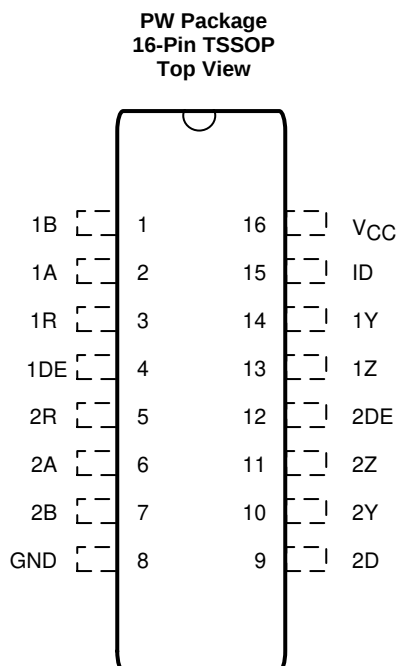
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4 修订历史记录

注：之前版本的页码可能与当前版本有所不同。

日期	修订版本	说明
2019 年 7 月	*	初始发行版。

5 Pin Configuration and Functions



Pin Functions

PIN		I/O	DESCRIPTION
NAME	NO.		
1A	2	I	RS422 differential input (noninverting) to receiver 1
2A	6	I	RS422 differential input (noninverting) to receiver 2
1B	1	I	RS422 differential input (inverting) to receiver 1
2B	7	I	RS422 differential input (inverting) to receiver 2
1D	15	I	Logic data input to RS422 driver 1
2D	9	I	Logic data input to RS422 driver 2
1DE	4	I	Driver 1 enable (active high)
2DE	12	I	Driver 2 enable (active high)
GND	8	—	Device ground
1R	3	O	Logic data output of RS422 receiver 1
2R	5	O	Logic data output of RS422 receiver 2
V _{CC}	16	—	Power supply
1Y	14	O	RS-422 differential (noninverting) driver output 1
2Y	10	O	RS-422 differential (noninverting) driver output 2
1Z	13	O	RS-422 differential (noninverting) driver output 1
2Z	11	O	RS-422 differential (noninverting) driver output 2

6 Specifications

6.1 Absolute Maximum Ratings

over recommended operating free-air temperature range (unless otherwise noted)⁽¹⁾

			MIN	MAX	UNIT
V _{CC}	Supply voltage ⁽²⁾		−0.5	7	V
V _I	Input voltage	Driver, DE, RE	−0.5	7	V
		A or B, Receiver	−14	14	
V _{ID}	Differential input voltage ⁽³⁾	Receiver	−14	14	V
V _O	Output voltage	Driver	−0.5	7	V
		Receiver	−0.5	V _{CC} + 0.5	
I _{IK}	Input clamp current	Driver, V _I < 0		−20	mA
I _{OK}	Output clamp current	Driver, V _O < 0		−20	mA
		Receiver	−20	20	
I _O	Output current	Driver	−150	150	mA
		Receiver	−25	25	
I _{CC}	Supply current			200	mA
	GND current			−200	mA
T _J	Operating virtual junction temperature			150	°C
T _{stg}	Storage temperature		−65	150	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) All voltage values except differential input voltage are with respect to the network GND.
- (3) Differential input voltage is measured at the noninverting terminal, with respect to the inverting terminal.

6.2 ESD Ratings

		VALUE	UNIT
V _(ESD)	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	±12000
		Charged-device model (CDM), per JEDEC specification JESD22-C101 ⁽²⁾	±1000
		IEC 61000-4-2, air-gap discharge	±8000
		IEC 61000-4-2, contact discharge	±8000

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

6.3 Recommended Operating Conditions

			MIN	NOM	MAX	UNIT
V _{CC}	Supply voltage		4.5	5	5.5	V
V _{IC}	Common-mode input voltage ⁽¹⁾	Receiver			±7	V
V _{ID}	Differential input voltage	Receiver			±7	V
V _I	Input voltage	Except A, B	0		5.5	V
V _O	Output voltage	Receiver	0		V _{CC}	V
V _{IH}	High-level input voltage	Except A, B	2			V
V _{IL}	Low-level input voltage	Except A, B			0.8	V
I _{OH}	High-level output current	Receiver			–6	mA
		Driver			–20	
I _{OL}	Low-level output current	Receiver			6	mA
		Driver			20	
T _A	Operating free-air temperature		–55		125	°C

(1) Refer to TIA/EIA-422-B for exact conditions.

6.4 Thermal Information

THERMAL METRIC ⁽¹⁾		SN65C1168E-SEP	UNIT
		PW (TSSOP)	
		16 PINS	
R _{θJA}	Junction-to-ambient thermal resistance	102.5	°C/W
R _{θJC(top)}	Junction-to-case (top) thermal resistance	32.3	°C/W
R _{θJB}	Junction-to-board thermal resistance	48.8	°C/W
ψ _{JT}	Junction-to-top characterization parameter	1.8	°C/W
ψ _{JB}	Junction-to-board characterization parameter	48.2	°C/W
R _{θJC(bot)}	Junction-to-case (bottom) thermal resistance	N/A	°C/W

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report, [SPRA953](#).

6.5 Driver Section Electrical Characteristics

over recommended supply voltage and operating free-air temperature ranges (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP ⁽¹⁾	MAX	UNIT
V _{IK}	Input clamp voltage	I _I = –18 mA			–1.5	V
V _{OH}	High-level output voltage	V _{IH} = 2 V, V _{IL} = 0.8 V, I _{OH} = –20 mA	2.4	3.5		V
V _{OL}	Low-level output voltage	V _{IH} = 2 V, V _{IL} = 0.8 V, I _{OL} = 20 mA		0.2	0.4	V
V _{OD1}	Differential output voltage 1	I _O = 0 mA	2		6	V
V _{OD2}	Differential output voltage 2	R _L = 100 Ω, see Figure 1 ⁽²⁾	2	3.7		V
Δ V _{OD}	Change in magnitude of differential output voltage	R _L = 100 Ω, see Figure 1 ⁽²⁾	–0.4		0.4	V
V _{OC}	Common-mode output voltage	R _L = 100 Ω, see Figure 1 ⁽²⁾	–3		3	V
Δ V _{OC}	Change in magnitude of common-mode output voltage	R _L = 100 Ω, see Figure 1 ⁽²⁾	–0.4		0.4	V
I _{O(OFF)}	Output current with power off	V _{CC} = 0 V			100	μA
					100	
I _{O(OFF)}	Output current with power off ⁽³⁾	V _{CC} = 0 V			3	mA
					3	
I _{OZ}	High-impedance-state output current	V _O = 2.5 V			20	μA
		V _O = 5 V			–20	
I _{OZ}	High-impedance-state output current ⁽³⁾	V _O = 2.5 V			2	mA
		V _O = 5 V			–2	
I _{IH}	High-level input current	V _I = V _{CC} or V _{IH}			1	μA
I _{IL}	Low-level input current	V _I = GND or V _{IL}			–36	μA
I _{OS}	Short-circuit output current	V _O = V _{CC} or GND ⁽⁴⁾	–30		–160	mA
I _{CC}	Supply current (total package)	No load, Enabled			4	mA
					5	
I _{CC}	Supply current (total package) ⁽³⁾	No load, Enabled			17	mA
					16	
C _i	Input capacitance			6		pF

(1) All typical values are at V_{CC} = 5 V and T_A = 25°C.

(2) Refer to TIA/EIA-422-B for exact conditions.

(3) 25°C only. Post 20-krad(Si) HDR TID using worst case static biasing.

(4) Not more than one output should be shorted at a time, and the duration of the short circuit should not exceed one second.

(5) This parameter is measured per input, while the other inputs are at V_{CC} or GND.

6.6 Receiver Section Electrical Characteristics

over recommended ranges of common-mode input voltage, supply voltage, and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP ⁽¹⁾	MAX	UNIT
V_{IT+}	Positive-going input threshold voltage, differential input				0.2	V
V_{IT-}	Negative-going input threshold voltage, differential input		-0.2 ⁽²⁾			V
V_{hys}	Input hysteresis ($V_{IT+} - V_{IT-}$)			60		mV
V_{OH}	High-level output voltage	$V_{ID} = 200$ mV, $I_{OH} = -6$ mA	3.8	4.2		V
V_{OL}	Low-level output voltage	$V_{ID} = -200$ mV, $I_{OL} = 6$ mA		0.1	0.3	V
I_I	Line input current	Other input at 0 V $V_I = 10$ V $V_I = -10$ V			1.5 -2.5	mA
r_I	Input resistance	$V_{IC} = -7$ V to 7 V, other input at 0 V	4	17		k Ω
I_{CC}	Supply current (total package)	No load, Enabled $V_I = V_{CC}$ or GND $V_{IH} = 2.4$ V or 0.5 V ⁽³⁾		4 5	6 9	mA
I_{CC}	Supply current (total package) ⁽⁴⁾	No load $V_I = V_{CC}$ or GND $V_I = 2.4$ or 0.5 V ⁽⁵⁾			17 16	mA

(1) All typical values are at $V_{CC} = 5$ V and $T_A = 25^\circ\text{C}$.

(2) The algebraic convention, where the less positive (more negative) limit is designated as minimum, is used in this data sheet for common-mode input voltage and threshold voltage levels only.

(3) Refer to TIA/EIA-422-B for exact conditions.

(4) 25°C only. Post 20-krad(Si) HDR TID using worst case static biasing.

(5) This parameter is measured per input, while the other inputs are at V_{CC} or GND.

6.7 Driver Section Switching Characteristics

over recommended supply voltage and operating free-air temperature ranges (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP ⁽¹⁾	MAX	UNIT
t_{PHL}	Propagation delay time, high- to low-level output	$R1 = R2 = 50$ Ω , $R3 = 500$ Ω , $C1 = C2 = C3 = 40$ pF, S1 is open, see Figure 2		8	16	ns
t_{PLH}	Propagation delay time, low- to high-level output			8	16	ns
$t_{sk(p)}$	Pulse skew			1.5	4	ns
t_r	Rise time	$R1 = R2 = 50$ Ω , $R3 = 500$ Ω , $C1 = C2 = C3 = 40$ pF, S1 is open, see Figure 3		5	8	ns
t_f	Fall time			5	8	ns
t_{PZH}	Output-enable time to high level	$R1 = R2 = 50$ Ω , $R3 = 500$ Ω , $C1 = C2 = C3 = 40$ pF, S1 is closed, see Figure 4		10	19	ns
t_{PZL}	Output-enable time to low level			10	19	ns
t_{PHZ}	Output-disable time from high level	$R1 = R2 = 50$ Ω , $R3 = 500$ Ω , $C1 = C2 = C3 = 40$ pF, S1 is closed, see Figure 4		7	16	ns
t_{PLZ}	Output-disable time from low level			7	16	ns
f_{SW}	Maximum switching frequency	$R1 = R2 = 50$ Ω , $R3 = 500$ Ω , $C1 = C2 = C3 = 40$ pF, S1 is open, see Figure 3	20			MHz

(1) All typical values are at $V_{CC} = 5$ V and $T_A = 25^\circ\text{C}$.

6.8 Receiver Section Switching Characteristics

over recommended operating free-air temperature range (unless otherwise noted)⁽¹⁾

PARAMETER		TEST CONDITIONS	MIN	TYP ⁽²⁾	MAX	UNIT
t _{PLH}	Propagation delay time, low- to high-level output	See Figure 5	9	15	27	ns
t _{PHL}	Propagation delay time, high- to low-level output	See Figure 5	9	15	27	ns
t _{TLH}	Transition time, low- to high-level output	V _{IC} = 0 V, see Figure 5		4	9	ns
t _{PHL}	Transition time, high- to low-level output			4	9	ns

(1) Measured per input while the other inputs are at V_{CC} or GND.

(2) All typical values are at V_{CC} = 5 V and T_A = 25°C.

7 Parameter Measurement Information

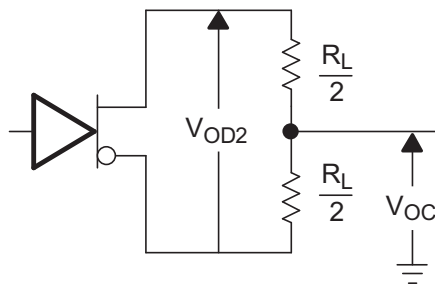
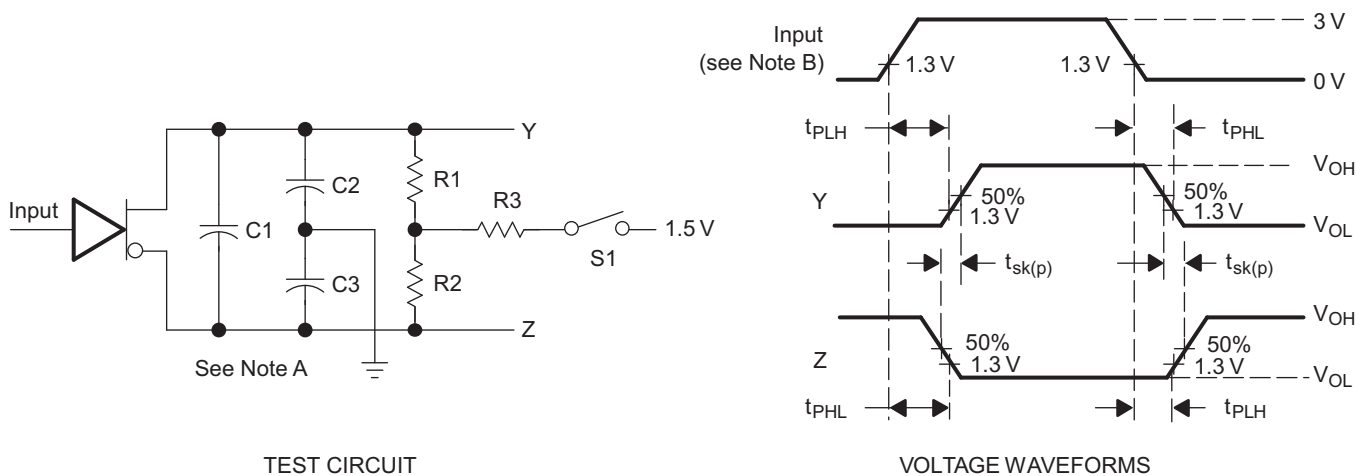
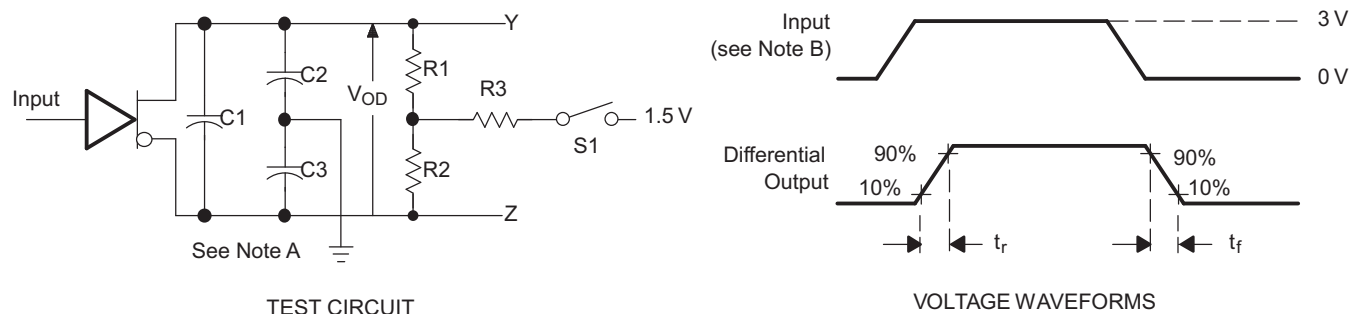


Figure 1. Driver Test Circuit, V_{OD} and V_{OC}



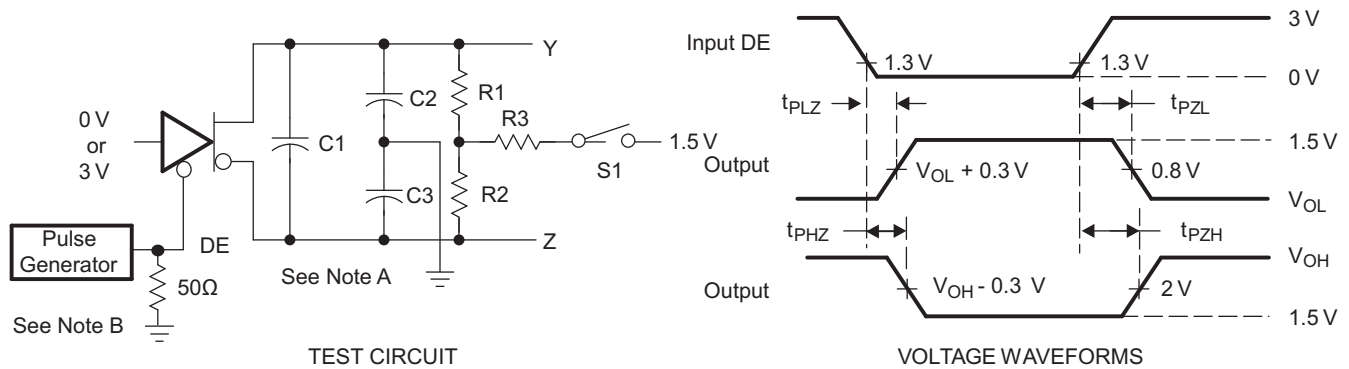
- A. C1, C2, and C3 include probe and jig capacitance.
- B. The input pulse is supplied by a generator having the following characteristics: PRR = 1 MHz, duty cycle = 50%, $t_r = t_f \leq 6$ ns.

Figure 2. Driver Test Circuit and Voltage Waveforms

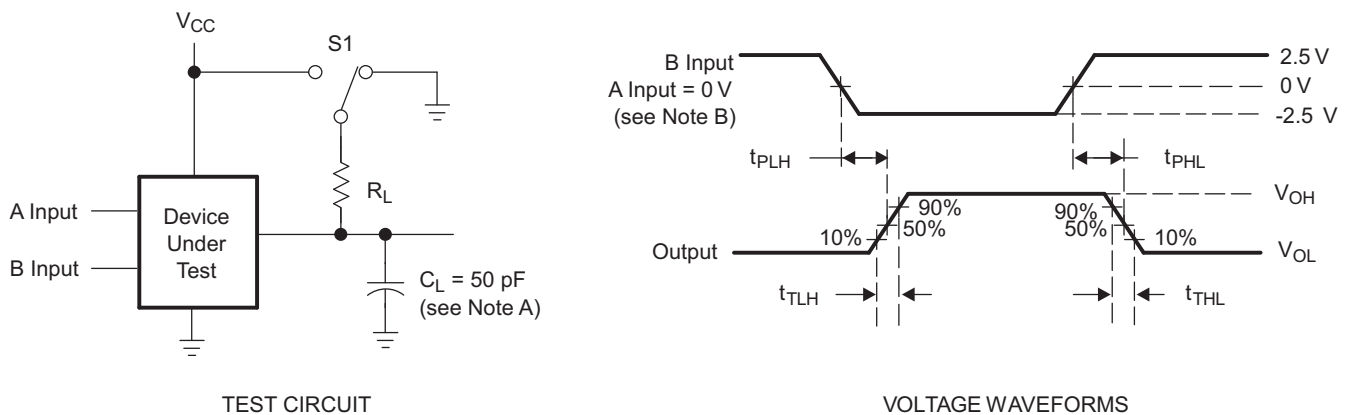


- A. C1, C2, and C3 include probe and jig capacitance.
- B. The input pulse is supplied by a generator having the following characteristics: PRR = 1 MHz, duty cycle = 50%, $t_r = t_f \leq 6$ ns.

Figure 3. Driver Test Circuit and Voltage Waveforms

Parameter Measurement Information (continued)


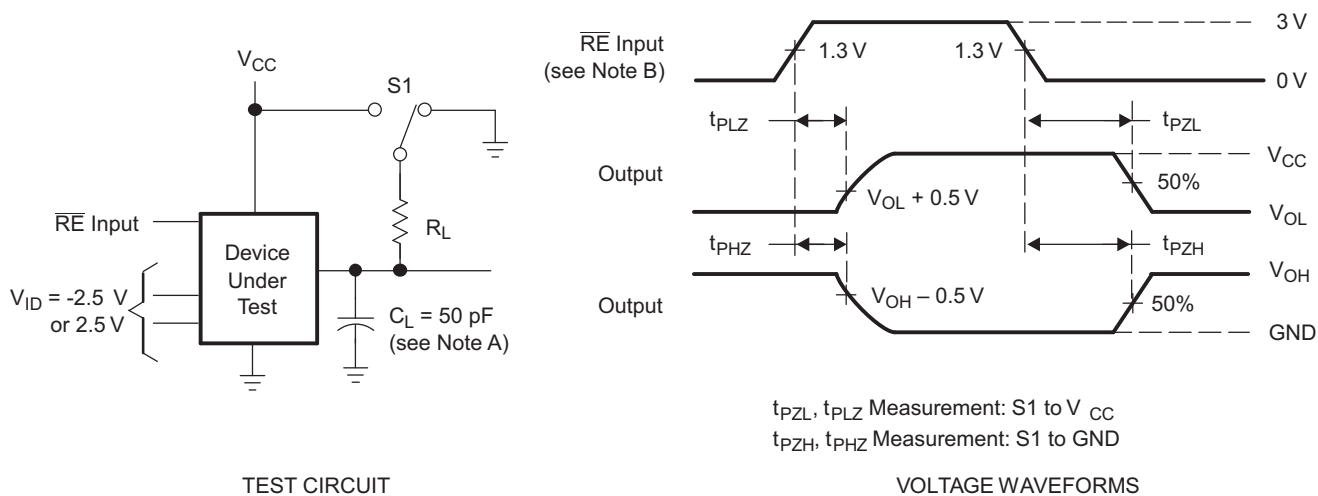
- A. C1, C2, and C3 include probe and jig capacitance.
- B. The input pulse is supplied by a generator having the following characteristics: PRR = 1 MHz, duty cycle = 50%, $t_r = t_f \leq 6$ ns.

Figure 4. Driver Test Circuit and Voltage Waveforms


- A. C1, C2, and C3 include probe and jig capacitance.
- B. The input pulse is supplied by a generator having the following characteristics: PRR = 1 MHz, duty cycle = 50%, $t_r = t_f \leq 6$ ns.

Figure 5. Receiver Test Circuit and Voltage Waveforms

Parameter Measurement Information (continued)



- A. C1, C2, and C3 include probe and jig capacitance.
- B. The input pulse is supplied by a generator having the following characteristics: PRR = 1 MHz, duty cycle = 50%, $t_r = t_f \leq 6$ ns.

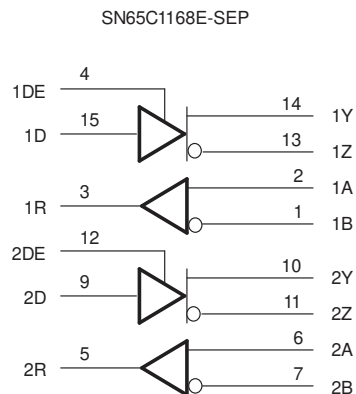
Figure 6. Receiver Test Circuit and Voltage Waveforms

8 Detailed Description

8.1 Overview

The SN65C1168E-SEP consist of dual drivers and dual receivers powered from a single 5-V supply. This device meets the requirements of TIA/EIA-422-B and ITU recommendation V.11.

8.2 Functional Block Diagram



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8.3 Feature Description

8.3.1 Active High Driver Output Enables

SN65C1168E-SEP drivers can be configured individually by 1DE and 2DE logic inputs. Both drivers are set at high-impedance when disabled.

8.4 Device Functional Modes

Table 1 and Table 2 lists the functional modes of SN65C1168E-SEP.

Table 1. Each Driver⁽¹⁾

INPUT D	ENABLE DE	OUTPUTS	
		Y	Z
H	H	H	L
L	H	L	H
X	L	Z	Z

(1) H = High level, L = Low level, X = Irrelevant, Z = High impedance (off)

Table 2. Each Receiver⁽¹⁾

DIFFERENTIAL INPUTS A-B	OUTPUT R
$V_{ID} \geq 0.2 \text{ V}$	H
$-0.2 \text{ V} < V_{ID} < 0.2 \text{ V}$	?
$V_{ID} \leq -0.2 \text{ V}$	L
Open	H

(1) H = High level, L = Low level, ? = Indeterminate

9 Application and Implementation

NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

9.1 Application Information

Figure 7 shows a typical RS-422 application. One transmitter is able to broadcast to multiple receiving nodes connected together over a shared differential bus. Twisted-pair cabling with a controlled differential impedance is used, and a termination resistance is placed at the farthest receive end of the cable in order to match the transmission line impedance and minimize signal reflections.

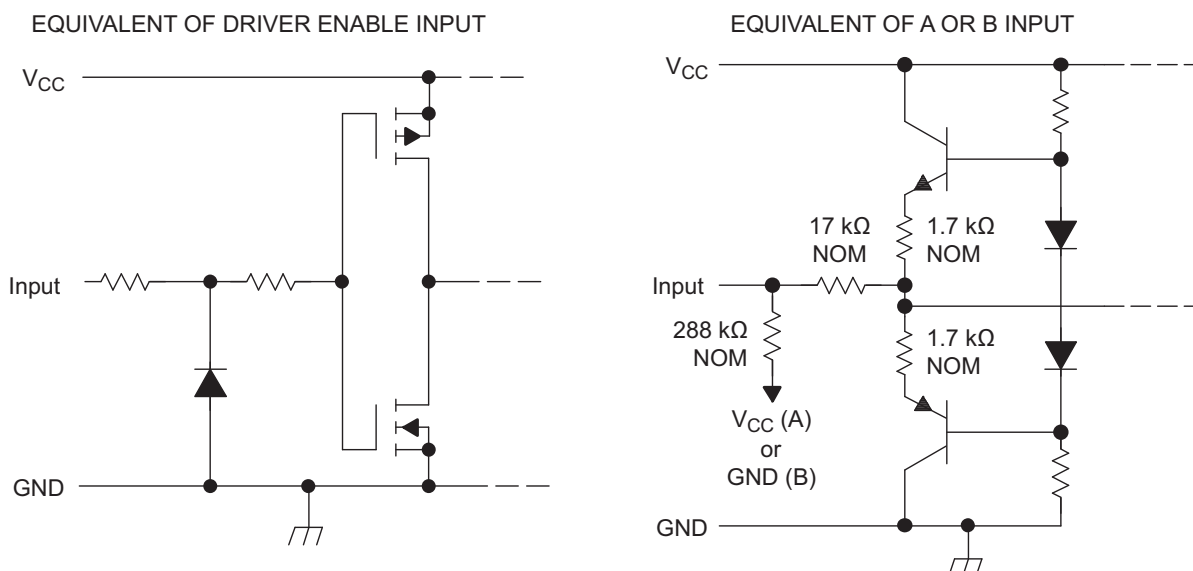


Figure 7. Schematic of Inputs

Application Information (continued)

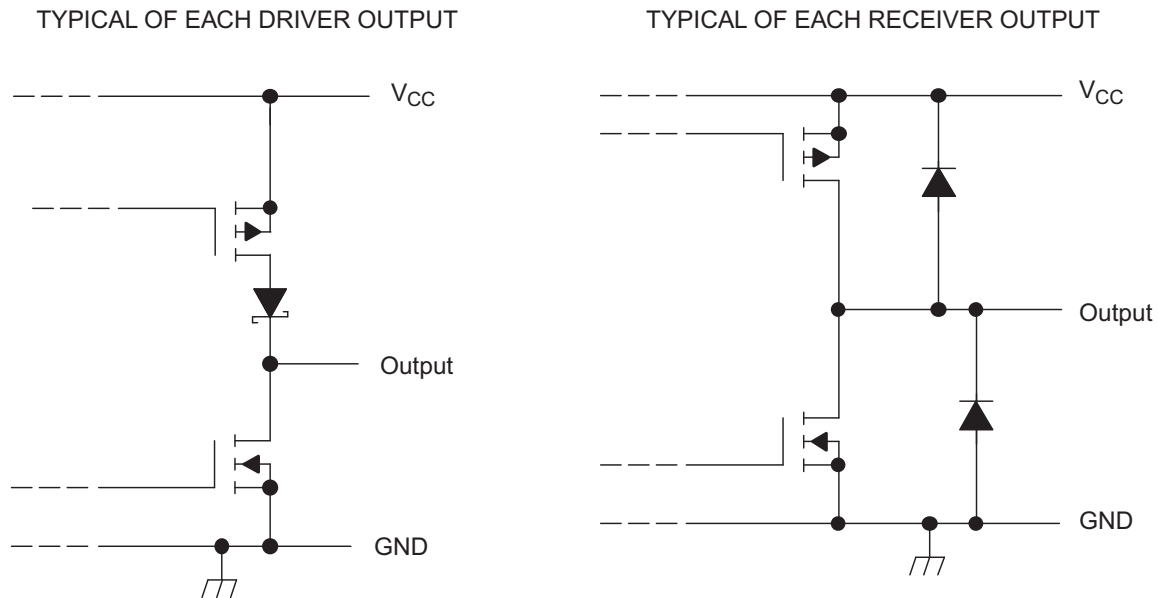


Figure 8. Schematic of Outputs

9.2 Typical Application

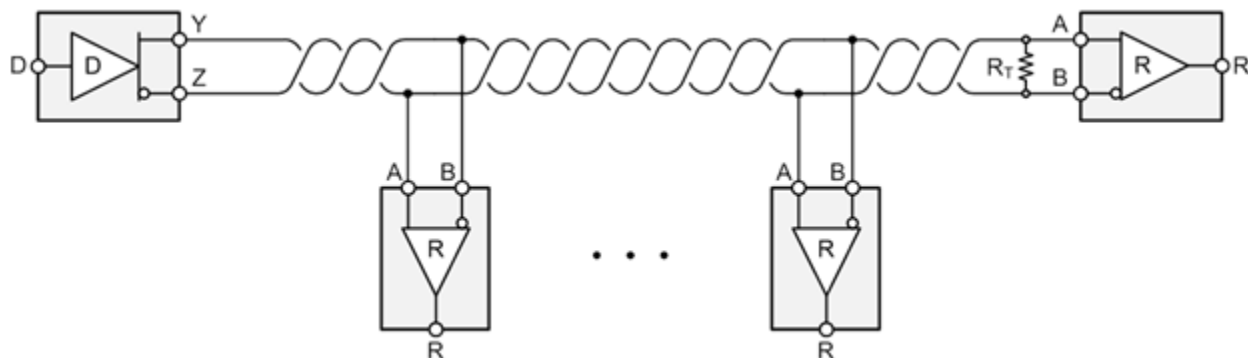


Figure 9. Typical RS-422 Application

9.2.1 Design Requirements

A typical RS-422 implementation using SN65C116xE requires the following:

- 5-V power source.
- Connector that ensures the correct polarity for port pins.
- Cabling that supports the desired operating rate and transmission distance.

9.2.2 Detailed Design Procedure

Place the device close to bus connector to keep traces (stub) short to prevent adding reflections to the bus line. If desired, add external fail-safe biasing to ensure ± 200 mV on the A-B port when the driver circuit is disabled.

10 Power Supply Recommendations

Use a 5-V power supply for V_{CC} place 0.1- μ F bypass capacitors close to the power supply pins to reduce errors coupling in from noisy or high impedance power supplies.

11 器件和文档支持

11.1 器件支持

11.1.1 第三方产品免责声明

TI 发布的与第三方产品或服务有关的信息，不能构成与此类产品或服务或保修的适用性有关的认可，不能构成此类产品或服务单独或与任何 TI 产品或服务一起的表示或认可。

11.2 接收文档更新通知

要接收文档更新通知，请导航至 TI.com.cn 上的器件产品文件夹。点击右上角的提醒我 (Alert me) 注册后，即可每周定期收到已更改的产品信息。有关更改的详细信息，请查看任何已修订文档中包含的修订历史记录。

11.3 社区资源

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

TI E2E™ Online Community *TI's Engineer-to-Engineer (E2E) Community*. Created to foster collaboration among engineers. At e2e.ti.com, you can ask questions, share knowledge, explore ideas and help solve problems with fellow engineers.

Design Support *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

11.4 商标

E2E is a trademark of Texas Instruments.
All other trademarks are the property of their respective owners.

11.5 静电放电警告



这些装置包含有限的内置 ESD 保护。存储或装卸时，应将导线一起截短或将装置放置于导电泡棉中，以防止 MOS 门极遭受静电损伤。

11.6 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

12 机械、封装和可订购信息

以下页面包含机械、封装和可订购信息。这些信息是指定器件的最新可用数据。数据如有变更，恕不另行通知，且不会对此文档进行修订。如需获取此数据表的浏览器版本，请查阅左侧的导航栏。

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
SN65C1168EMPWSEP	Active	Production	TSSOP (PW) 16	90 TUBE	Yes	NIPDAU	Level-3-260C-168 HR	-55 to 125	1168SEP
SN65C1168EMPWSEP.A	Active	Production	TSSOP (PW) 16	90 TUBE	Yes	NIPDAU	Level-3-260C-168 HR	-55 to 125	1168SEP
SN65C1168EMPWTSEP	Active	Production	TSSOP (PW) 16	250 SMALL T&R	Yes	NIPDAU	Level-3-260C-168 HR	-55 to 125	1168SEP
SN65C1168EMPWTSEP.A	Active	Production	TSSOP (PW) 16	250 SMALL T&R	Yes	NIPDAU	Level-3-260C-168 HR	-55 to 125	1168SEP
V62/19606-0XE	Active	Production	TSSOP (PW) 16	90 TUBE	-	NIPDAU	Level-3-260C-168 HR	-55 to 125	1168SEP
V62/19606-0XE-T	Active	Production	TSSOP (PW) 16	250 SMALL T&R	-	NIPDAU	Level-3-260C-168 HR	-55 to 125	1168SEP

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN65C1168EMPWTSEP	TSSOP	PW	16	250	180.0	12.4	6.9	5.6	1.6	8.0	12.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN65C1168EMPWTSEP	TSSOP	PW	16	250	210.0	185.0	35.0

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
SN65C1168EMPWSEP	PW	TSSOP	16	90	530	10.2	3600	3.5
SN65C1168EMPWSEP.A	PW	TSSOP	16	90	530	10.2	3600	3.5
V62/19606-0XE	PW	TSSOP	16	90	530	10.2	3600	3.5



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NOTES:

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153.

EXAMPLE BOARD LAYOUT

PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE: 10X



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NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0016A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE: 10X

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NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

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